# Digital Transistors (BRT)
# R1 = 100 kΩ, R2 = 100 kΩ

## PNP Transistors with Monolithic Bias Resistor Network

# MUN2136, MMUN2136L, MUN5136, DTA115EE, DTA115EM3

This series of digital transistors is designed to replace a single device and its external resistor bias network. The Bias Resistor Transistor (BRT) contains a single transistor with a monolithic bias network consisting of two resistors; a series base resistor and a base-emitter resistor. The BRT eliminates these individual components by integrating them into a single device. The use of a BRT can reduce both system cost and board space.
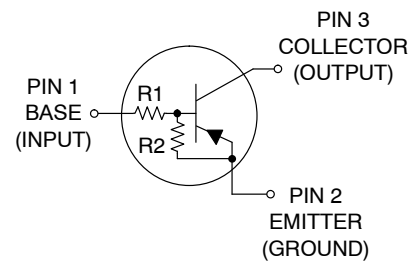
**Features**
- Simplifies Circuit Design
- Reduces Board Space
- Reduces Component Count
- S and NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant
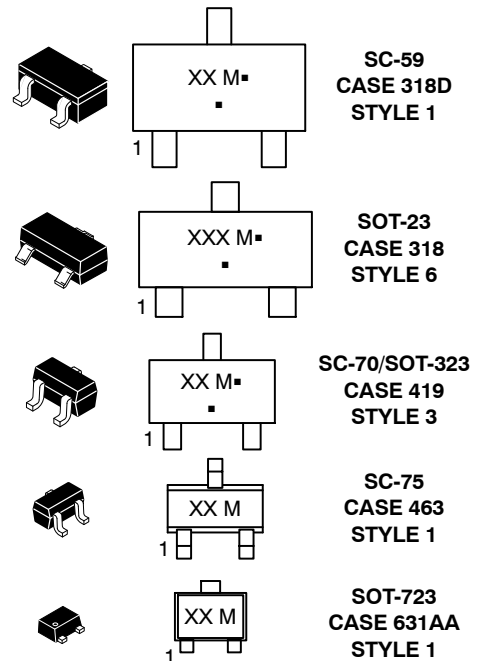
## MAXIMUM RATINGS ($T_A$ = 25 °C)

| Rating | Symbol | Max | Unit |
|---|---|---|---|
| Collector-Base Voltage | $V_{CBO}$ | 50 | Vdc |
| Collector-Emitter Voltage | $V_{CEO}$ | 50 | Vdc |
| Collector Current – Continuous | $I_C$ | 100 | mAdc |
| Input Forward Voltage | $V_{IN(fwd)}$ | 40 | Vdc |
| Input Reverse Voltage | $V_{IN(rev)}$ | 10 | Vdc |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

**PIN CONNECTIONS**

PIN 1 BASE (INPUT)
PIN 3 COLLECTOR (OUTPUT)
PIN 2 EMITTER (GROUND)
R1
R2

**MARKING DIAGRAMS**

| | |
|---|---|
| XX M■ | **SC-59 CASE 318D STYLE 1** |
| XXX M■ | **SOT-23 CASE 318 STYLE 6** |
| XX M■ | **SC-70/SOT-323 CASE 419 STYLE 3** |
| XX M | **SC-75 CASE 463 STYLE 1** |
| XX M | **SOT-723 CASE 631AA STYLE 1** |

XXX = Specific Device Code
M = Date Code*
■ = Pb-Free Package

(Note: Microdot may be in either location)

* Date Code orientation may vary depending upon manufacturing location.

## ORDERING INFORMATION

See detailed ordering, marking, and shipping information on page 2 of this data sheet.

# MUN2136, MMUN2136L, MUN5136, DTA115EE, DTA115EM3

**Table 1. ORDERING INFORMATION**

| Device | Part Marking | Package | Shipping† |
|---|---|---|---|
| MUN2136T1G | 6N | SC-59<br>(Pb-Free) | 3000 / Tape & Reel |
| MMUN2136LT1G, NSVMMUN2136LT1G* | ACG | SOT-23<br>(Pb-Free) | 3000 / Tape & Reel |
| MUN5136T1G, NSVMUN5136T1G* | 6N | SC-70/SOT-323<br>(Pb-Free) | 3000 / Tape & Reel |
| DTA115EET1G, NSVDTA115EET1G* | 6N | SC-75<br>(Pb-Free) | 3000 / Tape & Reel |
| DTA115EM3T5G | 6N | SOT-723<br>(Pb-Free) | 8000 / Tape & Reel |

† For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

\* S and NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable.
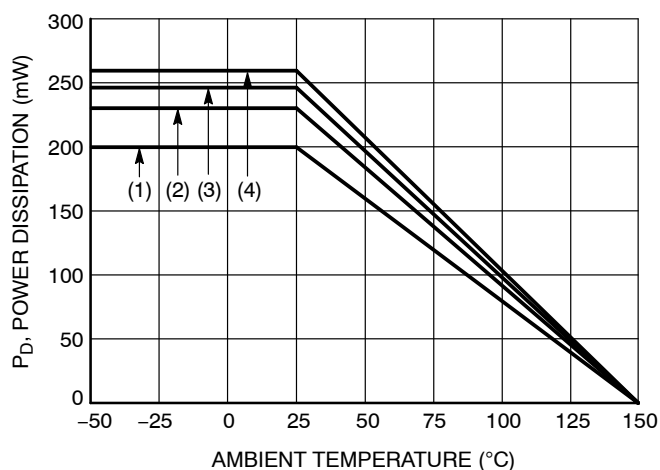


(1) SC-75 and SC-70/SOT323; Minimum Pad
(2) SC-59; Minimum Pad
(3) SOT-23; Minimum Pad
(4) SOT-723; Minimum Pad

**Figure 1. Derating Curve**

**Table 2. THERMAL CHARACTERISTICS**

| Characteristic | | Symbol | Max | Unit |
|---|---|---|---|---|
| **THERMAL CHARACTERISTICS (SC-59) (MUN2136)** | | | | |
| Total Device Dissipation<br>　$T_A$ = 25 °C　(Note 1)<br>　　　　　　(Note 2)<br>Derate above 25 °C　(Note 1)<br>　　　　　　(Note 2) | | $P_D$ | 230<br>338<br>1.8<br>2.7 | mW<br><br>mW/°C |
| Thermal Resistance,<br>　Junction to Ambient　(Note 1)<br>　　　　　　(Note 2) | | $R_{\theta JA}$ | 540<br>370 | °C/W |
| Thermal Resistance,<br>　Junction to Lead　(Note 1)<br>　　　　　　(Note 2) | | $R_{\theta JL}$ | 264<br>287 | °C/W |
| Junction and Storage Temperature Range | | $T_J, T_{stg}$ | −55 to +150 | °C |
| **THERMAL CHARACTERISTICS (SOT-23) (MMUN2136L)** | | | | |
| Total Device Dissipation<br>　$T_A$ = 25 °C　(Note 1)<br>　　　　　　(Note 2)<br>Derate above 25 °C　(Note 1)<br>　　　　　　(Note 2) | | $P_D$ | 246<br>400<br>2.0<br>3.2 | mW<br><br>mW/°C |
| Thermal Resistance,<br>　Junction to Ambient　(Note 1)<br>　　　　　　(Note 2) | | $R_{\theta JA}$ | 508<br>311 | °C/W |
| Thermal Resistance,<br>　Junction to Lead　(Note 1)<br>　　　　　　(Note 2) | | $R_{\theta JL}$ | 174<br>208 | °C/W |
| Junction and Storage Temperature Range | | $T_J, T_{stg}$ | −55 to +150 | °C |
| **THERMAL CHARACTERISTICS (SC-70/SOT-323) (MUN5136)** | | | | |
| Total Device Dissipation<br>　$T_A$ = 25 °C　(Note 1)<br>　　　　　　(Note 2)<br>Derate above 25 °C　(Note 1)<br>　　　　　　(Note 2) | | $P_D$ | 202<br>310<br>1.6<br>2.5 | mW<br><br>mW/°C |
| Thermal Resistance,<br>　Junction to Ambient　(Note 1)<br>　　　　　　(Note 2) | | $R_{\theta JA}$ | 618<br>403 | °C/W |
| Thermal Resistance,<br>　Junction to Lead　(Note 1)<br>　　　　　　(Note 2) | | $R_{\theta JL}$ | 280<br>332 | °C/W |
| Junction and Storage Temperature Range | | $T_J, T_{stg}$ | −55 to +150 | °C |
| **THERMAL CHARACTERISTICS (SC-75) (DTA115EE)** | | | | |
| Total Device Dissipation<br>　$T_A$ = 25 °C　(Note 1)<br>　　　　　　(Note 2)<br>Derate above 25 °C　(Note 1)<br>　　　　　　(Note 2) | | $P_D$ | 200<br>300<br>1.6<br>2.4 | mW<br><br>mW/°C |
| Thermal Resistance,<br>　Junction to Ambient　(Note 1)<br>　　　　　　(Note 2) | | $R_{\theta JA}$ | 600<br>400 | °C/W |
| Junction and Storage Temperature Range | | $T_J, T_{stg}$ | −55 to +150 | °C |
| **THERMAL CHARACTERISTICS (SOT-723) (DTA115EM3)** | | | | |
| Total Device Dissipation<br>　$T_A$ = 25 °C　(Note 1)<br>　　　　　　(Note 2)<br>Derate above 25 °C　(Note 1)<br>　　　　　　(Note 2) | | $P_D$ | 260<br>600<br>2.0<br>4.8 | mW<br><br>mW/°C |
| Thermal Resistance,<br>　Junction to Ambient　(Note 1)<br>　　　　　　(Note 2) | | $R_{\theta JA}$ | 480<br>205 | °C/W |
| Junction and Storage Temperature Range | | $T_J, T_{stg}$ | −55 to +150 | °C |

1. FR-4 @ Minimum Pad.
2. FR-4 @ 1.0 x 1.0 Inch Pad.

**Table 3. ELECTRICAL CHARACTERISTICS** ($T_A$ = 25 °C, unless otherwise noted)

| Characteristic | Symbol | Min | Typ | Max | Unit |
|---|---|---|---|---|---|
| **OFF CHARACTERISTICS** | | | | | |
| Collector-Base Cutoff Current<br>($V_{CB}$ = 50 V, $I_E$ = 0) | $I_{CBO}$ | – | – | 100 | nAdc |
| Collector-Emitter Cutoff Current<br>($V_{CE}$ = 50 V, $I_B$ = 0) | $I_{CEO}$ | – | – | 500 | nAdc |
| Emitter-Base Cutoff Current<br>($V_{EB}$ = 6.0 V, $I_C$ = 0) | $I_{EBO}$ | – | – | 0.05 | mAdc |
| Collector-Base Breakdown Voltage<br>($I_C$ = 10 μA, $I_E$ = 0) | $V_{(BR)CBO}$ | 50 | – | – | Vdc |
| Collector-Emitter Breakdown Voltage (Note 3)<br>($I_C$ = 2.0 mA, $I_B$ = 0) | $V_{(BR)CEO}$ | 50 | – | – | Vdc |
| **ON CHARACTERISTICS** | | | | | |
| DC Current Gain (Note 3)<br>($I_C$ = 5.0 mA, $V_{CE}$ = 10 V) | $h_{FE}$ | 80 | 150 | – | |
| Collector-Emitter Saturation Voltage (Note 3)<br>($I_C$ = 10 mA, $I_B$ = 0.3 mA) | $V_{CE(sat)}$ | – | – | 0.25 | Vdc |
| Input Voltage (off)<br>($V_{CE}$ = 5.0 V, $I_C$ = 100 μA) | $V_{i(off)}$ | – | 1.2 | 0.5 | Vdc |
| Input Voltage (on)<br>($V_{CE}$ = 0.3 V, $I_C$ = 1.0 mA) | $V_{i(on)}$ | 3.0 | 1.6 | – | Vdc |
| Output Voltage (on)<br>($V_{CC}$ = 5.0 V, $V_B$ = 5.5 V, $R_L$ = 1.0 kΩ) | $V_{OL}$ | – | – | 0.2 | Vdc |
| Output Voltage (off)<br>($V_{CC}$ = 5.0 V, $V_B$ = 0.5 V, $R_L$ = 1.0 kΩ) | $V_{OH}$ | 4.9 | – | – | Vdc |
| Input Resistor | R1 | 70 | 100 | 130 | kΩ |
| Resistor Ratio | $R_1/R_2$ | 0.8 | 1.0 | 1.2 | |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.
3. Pulsed Condition: Pulse Width = 300 ms, Duty Cycle ≤ 2%.

## TYPICAL CHARACTERISTICS
### MUN2136, MMUN2136L, MUN5136, DTA115EE, DTA115EM3
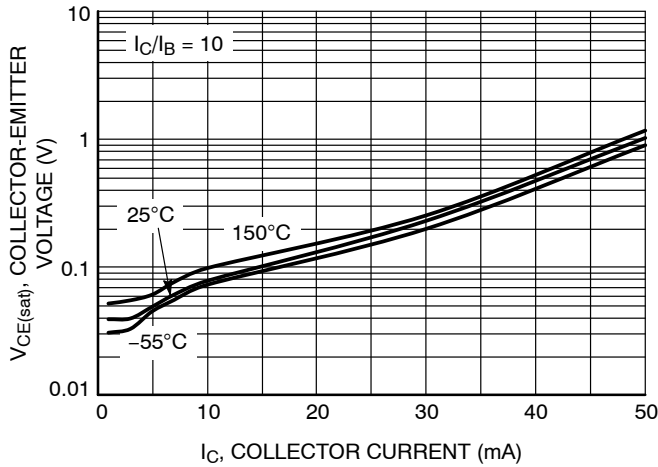
Figure 2. $V_{CE(sat)}$ vs. $I_C$
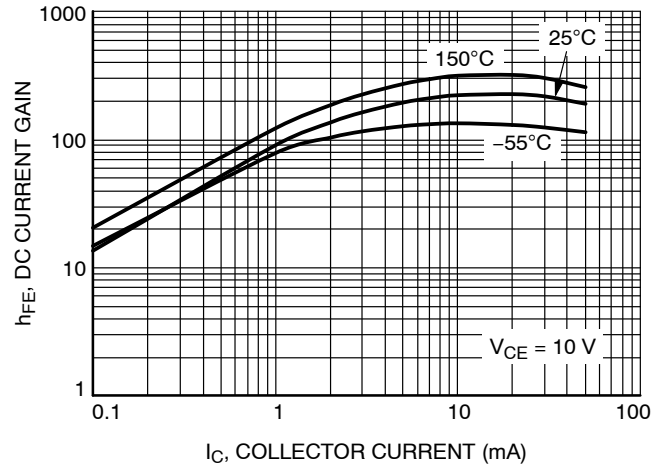
Figure 3. DC Current Gain
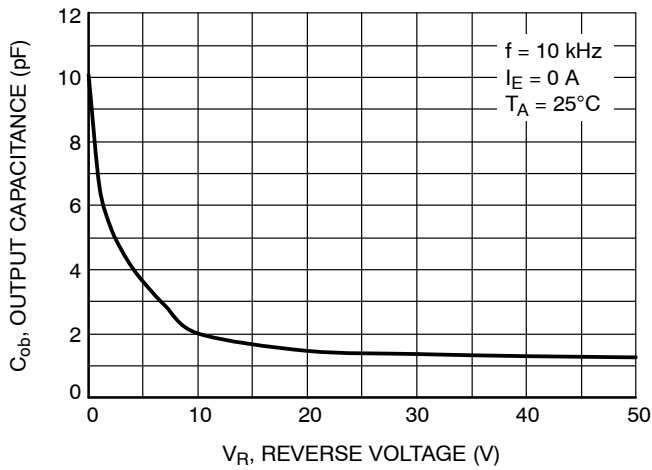
Figure 4. Output Capacitance
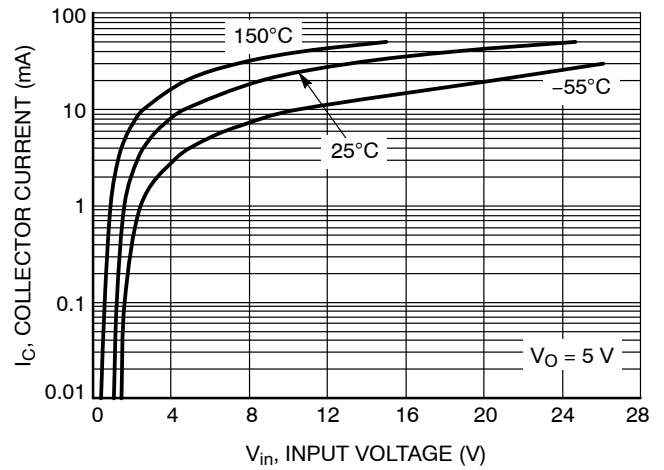
Figure 5. Output Current vs. Input Voltage
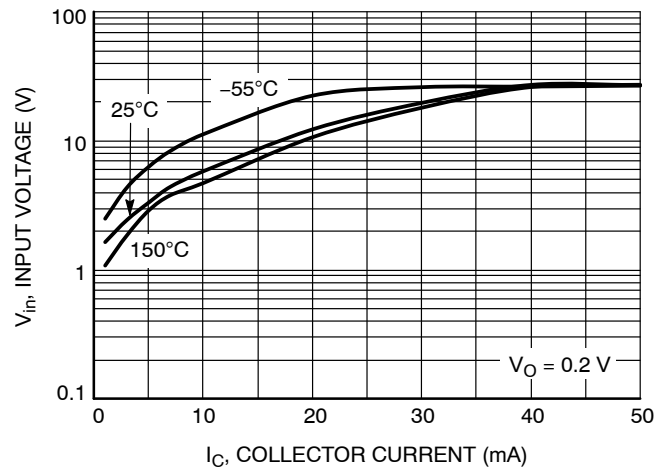
Figure 6. Input Voltage vs. Output Current

**REVISION HISTORY**

| Revision | Description of Changes | Date |
|---|---|---|
| 7 | Rebranded the Data Sheet to **onsemi** format. | 06/11/2025 |

## PACKAGE DIMENSIONS
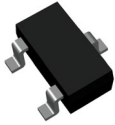
**SC−59−3 2.90x1.50x1.15, 1.90P**
CASE 318D
ISSUE J

DATE 15 FEB 2024
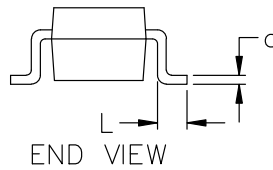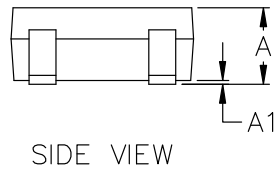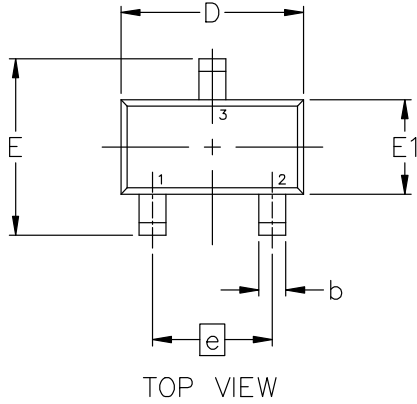
NOTES:

1. DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5−2018.
2. ALL DIMENSION ARE IN MILLIMETERS.

| DIM | MILLIMETERS | | |
|-----|------|------|------|
| | MIN. | NOM. | MAX. |
| A | 1.00 | 1.15 | 1.30 |
| A1 | 0.01 | 0.06 | 0.10 |
| b | 0.35 | 0.43 | 0.50 |
| c | 0.09 | 0.14 | 0.18 |
| D | 2.70 | 2.90 | 3.10 |
| E | 2.50 | 2.80 | 3.00 |
| E1 | 1.30 | 1.50 | 1.70 |
| e | 1.90 BSC | | |
| L | 0.20 | 0.40 | 0.60 |
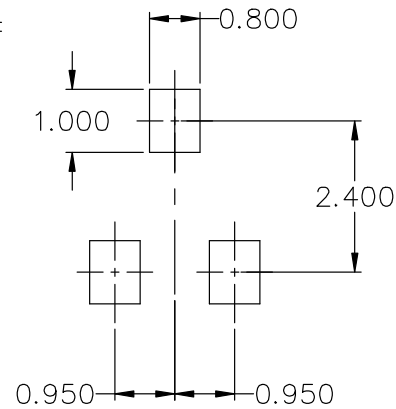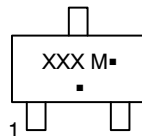
TOP VIEW

SIDE VIEW

END VIEW

RECOMMENDED MOUNTING FOOTPRINT*

0.800

1.000

2.400

0.950  0.950

\*  FOR ADDITIONAL INFORMATION ON OUR Pb−FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

**GENERIC
MARKING DIAGRAM***

XXX M▪

1

XXX    = Specific Device Code
M       = Date Code
▪        = Pb−Free Package*

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

STYLE 1:
PIN 1. BASE
    2. EMITTER
    3. COLLECTOR

STYLE 2:
PIN 1. ANODE
    2. N.C.
    3. CATHODE

STYLE 3:
PIN 1. ANODE
    2. ANODE
    3. CATHODE

STYLE 4:
PIN 1. CATHODE
    2. N.C.
    3. ANODE

STYLE 5:
PIN 1. CATHODE
    2. CATHODE
    3. ANODE

STYLE 6:
PIN 1. ANODE
    2. CATHODE
    3. ANODE/CATHODE
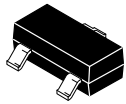
**SOT−23 (TO−236) 2.90x1.30x1.00 1.90P**
CASE 318
ISSUE AU

DATE 14 AUG 2024

SCALE 4:1

TOP VIEW

DETAIL "A"
Scale 3:1

SIDE VIEW

DETAIL "A"

END VIEW

SEATING PLANE
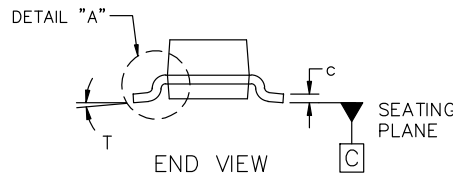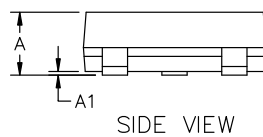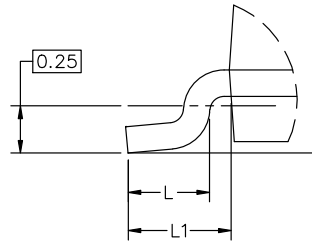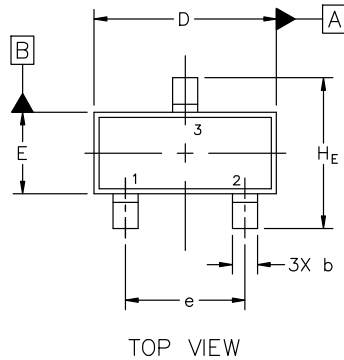
| DIM | MILLIMETERS | | |
|-----|-----|-----|-----|
| | MIN | NOM | MAX |
| A | 0.89 | 1.00 | 1.11 |
| A1 | 0.01 | 0.06 | 0.10 |
| b | 0.37 | 0.44 | 0.50 |
| c | 0.08 | 0.14 | 0.20 |
| D | 2.80 | 2.90 | 3.04 |
| E | 1.20 | 1.30 | 1.40 |
| e | 1.78 | 1.90 | 2.04 |
| L | 0.30 | 0.43 | 0.55 |
| L1 | 0.35 | 0.54 | 0.69 |
| $H_E$ | 2.10 | 2.40 | 2.64 |
| T | 0° | −−− | 10° |

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2018.
2. CONTROLLING DIMENSIONS: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

**GENERIC MARKING DIAGRAM\***
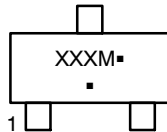
XXXM▪

XXX = Specific Device Code
M = Date Code
▪ = Pb−Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.
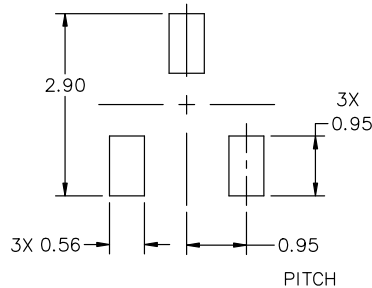
RECOMMENDED MOUNTING FOOTPRINT

\* For additional information on our Pb−Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

**STYLES ON PAGE 2**

| **DOCUMENT NUMBER:** | 98ASB42226B | Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red. | |
|-----|-----|-----|-----|
| **DESCRIPTION:** | **SOT−23 (TO−236) 2.90x1.30x1.00 1.90P** | | **PAGE 1 OF 2** |

STYLE 1 THRU 5:
CANCELLED

STYLE 6:
PIN 1. BASE
2. EMITTER
3. COLLECTOR

STYLE 7:
PIN 1. EMITTER
2. BASE
3. COLLECTOR

STYLE 8:
PIN 1. ANODE
2. NO CONNECTION
3. CATHODE

STYLE 9:
PIN 1. ANODE
2. ANODE
3. CATHODE

STYLE 10:
PIN 1. DRAIN
2. SOURCE
3. GATE

STYLE 11:
PIN 1. ANODE
2. CATHODE
3. CATHODE−ANODE

STYLE 12:
PIN 1. CATHODE
2. CATHODE
3. ANODE

STYLE 13:
PIN 1. SOURCE
2. DRAIN
3. GATE

STYLE 14:
PIN 1. CATHODE
2. GATE
3. ANODE

STYLE 15:
PIN 1. GATE
2. CATHODE
3. ANODE

STYLE 16:
PIN 1. ANODE
2. CATHODE
3. CATHODE

STYLE 17:
PIN 1. NO CONNECTION
2. ANODE
3. CATHODE

STYLE 18:
PIN 1. NO CONNECTION
2. CATHODE
3. ANODE

STYLE 19:
PIN 1. CATHODE
2. ANODE
3. CATHODE−ANODE

STYLE 20:
PIN 1. CATHODE
2. ANODE
3. GATE

STYLE 21:
PIN 1. GATE
2. SOURCE
3. DRAIN

STYLE 22:
PIN 1. RETURN
2. OUTPUT
3. INPUT

STYLE 23:
PIN 1. ANODE
2. ANODE
3. CATHODE

STYLE 24:
PIN 1. GATE
2. DRAIN
3. SOURCE

STYLE 25:
PIN 1. ANODE
2. CATHODE
3. GATE

STYLE 26:
PIN 1. CATHODE
2. ANODE
3. NO CONNECTION

STYLE 27:
PIN 1. CATHODE
2. CATHODE
3. CATHODE

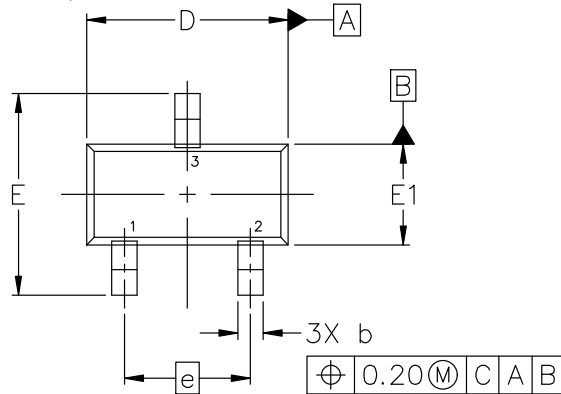STYLE 28:
PIN 1. ANODE
2. ANODE
3. ANODE

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|---|---|---|---|
| DESCRIPTION: | SOT−23 (TO−236) 2.90x1.30x1.00 1.90P | | **PAGE 2 OF 2** |

**SC−70 (SOT−323)**
CASE 419
ISSUE R

DATE 11 OCT 2022

SCALE 4:1

D

H_E

3

E

1    2

b

e

TOP VIEW

A

0.05 (0.002)

A1

SIDE VIEW

A2

L

C

END VIEW
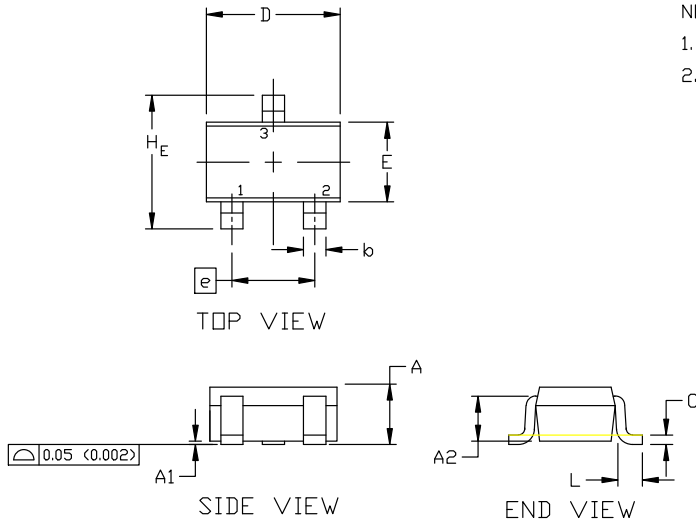
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1982.

2. CONTROLLING DIMENSION: INCH

| DIM | MILLIMETERS | | | INCHES | | |
|-----|------|------|------|------|------|------|
| | MIN. | NOM. | MAX. | MIN. | NOM. | MAX. |
| A | 0.80 | 0.90 | 1.00 | 0.032 | 0.035 | 0.040 |
| A1 | 0.00 | 0.05 | 0.10 | 0.000 | 0.002 | 0.004 |
| A2 | 0.70 REF | | | 0.028 BSC | | |
| b | 0.30 | 0.35 | 0.40 | 0.012 | 0.014 | 0.016 |
| c | 0.10 | 0.18 | 0.25 | 0.004 | 0.007 | 0.010 |
| D | 1.80 | 2.00 | 2.20 | 0.071 | 0.080 | 0.087 |
| E | 1.15 | 1.24 | 1.35 | 0.045 | 0.049 | 0.053 |
| e | 1.20 | 1.30 | 1.40 | 0.047 | 0.051 | 0.055 |
| e1 | 0.65 BSC | | | 0.026 BSC | | |
| L | 0.20 | 0.38 | 0.56 | 0.008 | 0.015 | 0.022 |
| H_E | 2.00 | 2.10 | 2.40 | 0.079 | 0.083 | 0.095 |
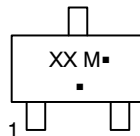
0.65 [0.025]

0.65 [0.025]

1.90 [0.075]

0.90 [0.035]

0.70 [0.028]

SOLDERING FOOTPRINT

\*  For additional information on our Pb−Free
strategy and soldering details, please download
the ON Semiconductor Soldering and Mounting
Techniques Reference Manual, SOLDERRM/D.
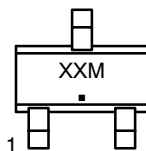
**GENERIC**
**MARKING DIAGRAM**

XX M■
•

1

XX    = Specific Device Code
M     = Date Code
■     = Pb−Free Package

*This information is generic. Please refer to
device data sheet for actual part marking.
Pb−Free indicator, "G" or microdot "■", may
or may not be present. Some products may
not follow the Generic Marking.
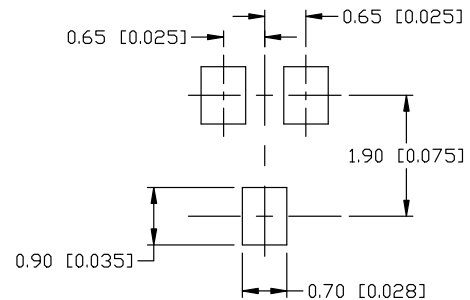
STYLE 1:
    CANCELLED

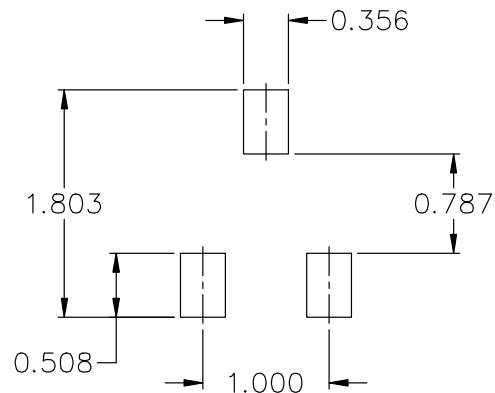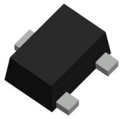STYLE 2:
    PIN 1. ANODE
        2. N.C.
        3. CATHODE

STYLE 3:
    PIN 1. BASE
        2. EMITTER
        3. COLLECTOR

STYLE 4:
    PIN 1. CATHODE
        2. CATHODE
        3. ANODE

STYLE 5:
    PIN 1. ANODE
        2. ANODE
        3. CATHODE

STYLE 6:
    PIN 1. EMITTER
        2. BASE
        3. COLLECTOR

STYLE 7:
    PIN 1. BASE
        2. EMITTER
        3. COLLECTOR

STYLE 8:
    PIN 1. GATE
        2. SOURCE
        3. DRAIN

STYLE 9:
    PIN 1. ANODE
        2. CATHODE
        3. CATHODE-ANODE

STYLE 10:
    PIN 1. CATHODE
        2. ANODE
        3. ANODE-CATHODE

STYLE 11:
    PIN 1. CATHODE
        2. CATHODE
        3. CATHODE

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|---|---|---|
| **DESCRIPTION:** | SC−70 (SOT−323) | **PAGE 1 OF 1** |

**SC75−3 1.60x0.80x0.80, 1.00P**
CASE 463
ISSUE H

DATE 01 FEB 2024

NOTES:

1. DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5−2018.
2. ALL DIMENSION ARE IN MILLIMETERS.

TOP VIEW

3X b

⊕ | 0.20 Ⓜ | C | A | B

SIDE VIEW

SEATING PLANE

END VIEW

| DIM | MILLIMETERS | | |
|-----|------|------|------|
|     | MIN. | NOM. | MAX. |
| A   | 0.70 | 0.80 | 0.90 |
| A1  | 0.00 | 0.05 | 0.10 |
| A2  | 0.80 REF. | | |
| b   | 0.15 | 0.20 | 0.30 |
| c   | 0.10 | 0.15 | 0.25 |
| D   | 1.55 | 1.60 | 1.65 |
| E   | 1.50 | 1.60 | 1.70 |
| E1  | 0.70 | 0.80 | 0.90 |
| e   | 1.00 BSC | | |
| L   | 0.10 | 0.15 | 0.20 |

**GENERIC MARKING DIAGRAM***

XXM

XX = Specific Device Code
M = Date Code
▪ = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

STYLE 1:
PIN 1. BASE
2. EMITTER
3. COLLECTOR

STYLE 2:
PIN 1. ANODE
2. N/C
3. CATHODE

STYLE 3:
PIN 1. ANODE
2. ANODE
3. CATHODE

STYLE 4:
PIN 1. CATHODE
2. CATHODE
3. ANODE

STYLE 5:
PIN 1. GATE
2. SOURCE
3. DRAIN

0.356

1.803

0.787

0.508

1.000

RECOMMENDED MOUNTING FOOTPRINT*

* FOR ADDITIONAL INFORMATION ON OUR Pb−FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

| **DOCUMENT NUMBER:** | **98ASB15184C** | | |
|---|---|---|---|
| **DESCRIPTION:** | **SC75−3 1.60x0.80x0.80, 1.00P** | | **PAGE 1 OF 1** |

**onsemi**

**SOT−723 1.20x0.80x0.50, 0.40P**
CASE 631AA
ISSUE E

DATE 24 JAN 2024

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2018.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
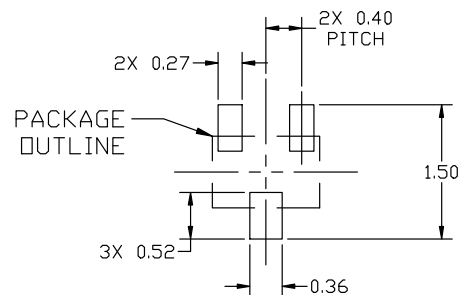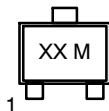4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
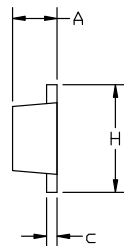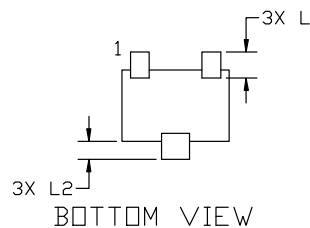
| DIM | MILLIMETERS | | |
|-----|------|------|------|
|     | MIN. | NOM. | MAX. |
| A | 0.45 | 0.50 | 0.55 |
| b | 0.15 | 0.21 | 0.27 |
| b1 | 0.25 | 0.31 | 0.37 |
| c | 0.07 | 0.12 | 0.17 |
| D | 1.15 | 1.20 | 1.25 |
| E | 0.75 | 0.80 | 0.85 |
| e | 0.40 BSC | | |
| H | 1.15 | 1.20 | 1.25 |
| L | 0.29 REF | | |
| L2 | 0.15 | 0.20 | 0.25 |

TOP VIEW

SIDE VIEW

BOTTOM VIEW

RECOMMENDED MOUNTING FOOTPRINT

2X 0.40 PITCH
2X 0.27
PACKAGE OUTLINE
1.50
3X 0.52
0.36

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

**GENERIC MARKING DIAGRAM\***

XX M

XX = Specific Device Code
M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

STYLE 1:
PIN 1. BASE
2. EMITTER
3. COLLECTOR

STYLE 2:
PIN 1. ANODE
2. N/C
3. CATHODE

STYLE 3:
PIN 1. ANODE
2. ANODE
3. CATHODE

STYLE 4:
PIN 1. CATHODE
2. CATHODE
3. ANODE

STYLE 5:
PIN 1. GATE
2. SOURCE
3. DRAIN

| DOCUMENT NUMBER: | 98AON12989D | | |
|---|---|---|---|
| DESCRIPTION: | SOT−723 1.20x0.80x0.50, 0.40P | | PAGE 1 OF 1 |

## ADDITIONAL INFORMATION

**TECHNICAL PUBLICATIONS**:
**Technical Library:** www.onsemi.com/design/resources/technical–documentation
**onsemi Website:** www.onsemi.com

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www.onsemi.com/support/sales

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